



## Material Content Data Sheet



<b>Sales Product Name</b>		ESD311-U1-02N E6327		<b>Issued</b>		19. July 2018		
<b>MA#</b>		MA001213862						
<b>Package</b>		PG-TSNP-2-2		<b>Weight*</b>		1.88 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.105	5.58	5.58	55838	55838
leadframe	non noble metal	zinc	7440-66-6	0.002	0.10		1043	
	non noble metal	tin	7440-31-5	0.002	0.13		1304	
	non noble metal	chromium	7440-47-3	0.003	0.16		1565	
wire	non noble metal	copper	7440-50-8	0.974	51.81	52.20	517877	521789
	non noble metal	copper	7440-50-8	0.003	0.17	0.17	1748	1748
encapsulation	organic material	carbon black	1333-86-4	0.003	0.17		1731	
	plastics	epoxy resin	-	0.094	5.02		50192	
	inorganic material	silicondioxide	60676-86-0	0.554	29.42	34.61	294232	346155
leadfinish	non noble metal	tin	7440-31-5	0.055	2.90	2.90	29039	29039
plating	noble metal	silver	7440-22-4	0.022	1.17	1.17	11708	11708
glue	plastics	epoxy resin	-	0.013	0.67		6744	
	noble metal	silver	7440-22-4	0.051	2.70	3.37	26979	33723
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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